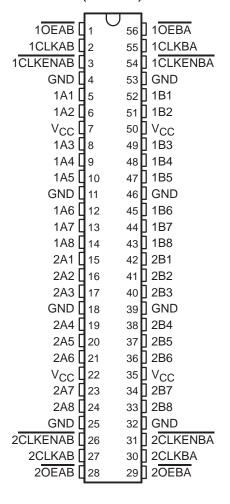
- Members of the Texas Instruments
 Widebus™ Family
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Lavout
- High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OI})
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

description

The 'ABT16470 are 16-bit registered transceivers that contain two sets of D-type flip-flops for temporary storage of data flowing in either direction. The 'ABT16470 can be used as two 8-bit transceivers or one 16-bit transceiver. Separate clock (CLKAB or CLKBA) and output-enable (OEAB or OEBA) inputs are provided for each register to permit independent control in either direction of data flow.

To avoid false clocking of the flip-flops, clock enable (CLKEN) should not be switched from high to low while CLK is high.

SN54ABT16470 . . . WD PACKAGE SN74ABT16470 . . . DGG OR DL PACKAGE (TOP VIEW)



To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16470 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16470 is characterized for operation from –40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus and EPIC-IIB are trademarks of Texas Instruments Incorporated.



SN54ABT16470, SN74ABT16470 16-BIT REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS SCBS085E - FEBRUARY 1991 - REVISED MAY 1997

FUNCTION TABLE†

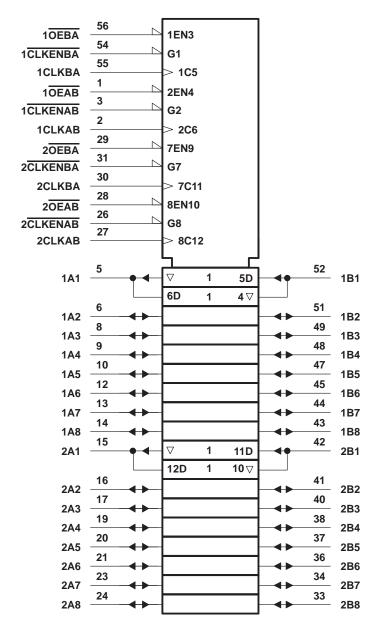
	INPUT	S		OUTPUT
CLKENAB	CLKAB	OEAB	Α	В
Н	Х	Χ	Χ	Z
Х	Χ	Н	X	Z
L	L	L	Χ	в ₀ ‡
L	\uparrow	L	L	L
L	\uparrow	L	Н	Н

[†] A-to-B data flow is shown: B-to-A flow is similar but uses CLKENBA, CLKBA, and OEBA.



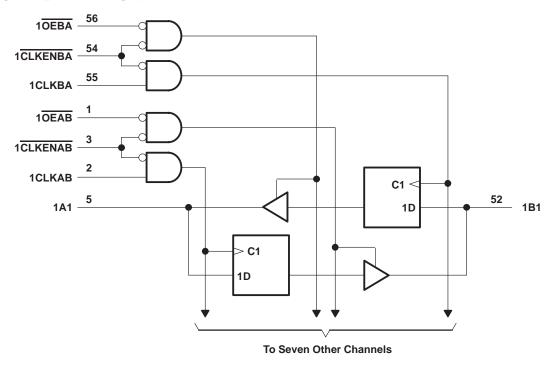
[‡]Output level before the indicated steady-state input conditions were established

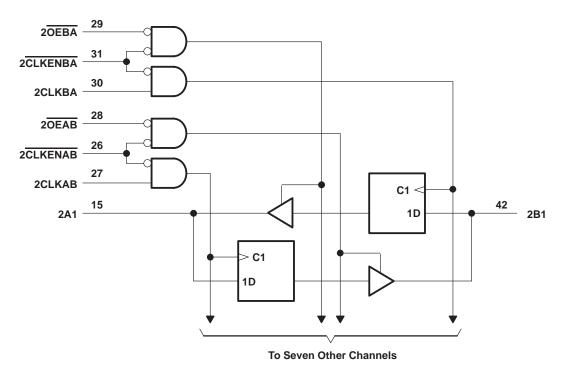
logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)







absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, VO	$-0.5\ V$ to 5.5 V
Current into any output in the low state, I _O : SN54ABT16470	96 mA
SN74ABT16470	128 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 2): DGG package	81°C/W
DL package	74°C/W
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			SN54ABT	16470	SN74AB1	16470	UNIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2	EM	2		V	
VIL	V _{IL} Low-level input voltage					0.8	V
٧ _I	Input voltage		0 0	VCC	0	VCC	V
loh	High-level output current		40,	-24		-32	mA
loL	I _{OL} Low-level output current					64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	B	10		10	ns/V
TA	Operating free-air temperature	– 55	125	-40	85	°C	

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

SN54ABT16470, SN74ABT16470 16-BIT REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS085E - FEBRUARY 1991 - REVISED MAY 1997

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DA	RAMETER	TEST COM	IDITIONS	Т	A = 25°C	;	SN54AB	Γ16470	SN74AB1	16470	UNIT	
PA	RAWETER	1EST COR	ADITIONS	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII	
VIK		$V_{CC} = 4.5 \text{ V},$	I _I = -18 mA			-1.2		-1.2		-1.2	V	
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5			
\/a		$V_{CC} = 5 V$,	$I_{OH} = -3 \text{ mA}$	3			3		3		V	
VOH		V _{CC} = 4.5 V	$I_{OH} = -24 \text{ mA}$	2			2				v	
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2			
VOL		V _{CC} = 4.5 V	$I_{OL} = 48 \text{ mA}$			0.55		0.55			V	
VOL		VCC = 4.5 V	$I_{OL} = 64 \text{ mA}$			0.55*				0.55	V	
V_{hys}					100			JE.			mV	
Control inputs VCC		V _{CC} = 5.5 V,	V _I = V _{CC} or GND			±1		±1		±1	μΑ	
<u>'</u> '	A or B ports	vCC = 5.5 v,	AL = ACC OLGIAD			±100	4	±100		±100	μΑ	
lozh [‡]		$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.7 \text{ V}$			50	, '0,	50		50	μΑ	
l _{OZL} ‡		$V_{CC} = 5.5 \text{ V},$	$V_0 = 0.5 V$			- 50	² QC	- 50		– 50	μΑ	
l _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 V$			±100	Q'			±100	μΑ	
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μА	
IO§		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-200	- 50	-200	-50	-200	mA	
		V _{CC} = 5.5 V,	Outputs high			2		2		2		
ICC	A or B ports	$I_O = 0$,	Outputs low			35		35		35	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled			2		2		2		
ΔICC¶		V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND				0.5		0.5		0.5	mA	
Ci	Control inputs	V _I = 2.5 V or 0.5 V			3						pF	
Cio	A or B ports	$V_0 = 2.5 \text{ V or } 0.5 \text{ V}$			8.5						pF	

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		V _{CC} :	= 5 V, 25°C	SN54AB	T16470	SN74ABT16470		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency	0	150	0	150	0	150	MHz
t _W #	Pulse duration, CLKAB or CLKBA high or low	3.3		3.3	16.10	3.3		ns
t _{su}	Setup time, data before CLKAB↑ or CLKBA↑	4		4	7.	4		ns
t _h	Hold time, data after CLKAB↑ or CLKBA↑	1		Ŷ1		1	·	ns

[#]This parameter is characterized, but not production tested.



[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] The parameters IOZH and IOZL include the input leakage current.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

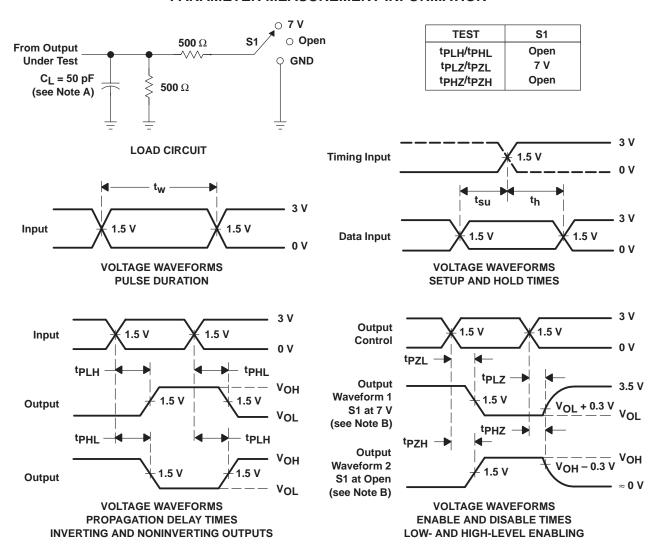
SN54ABT16470, SN74ABT16470 16-BIT REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS085E - FEBRUARY 1991 - REVISED MAY 1997

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V ₍	CC = 5 V 4 = 25°C	', ;	SN54AB	Г16470	SN74AB1	Г16470	UNIT
	(1141 01)	(0011 01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f _{max}			150			150		150		MHz
t _{PLH}	CLK	A or B	1.4	3.1	4.8	1.4	5.1	1.4	4.9	
^t PHL	CLK	AUIB	1.3	3.2	4.6	1.3	5.1	1.3	4.9	ns
^t PZH	ŌĒ	A or B	1	3.1	4.3	1	5	1	4.9	ns
t _{PZL}	OE		1.2	3.6	5.8	1.2	6.9	1.2	6.8	115
^t PHZ	ŌĒ	A or B	1.9	3.7	4.9	1.9	6	1.9	5.5	20
^t PLZ] 06	AOIB	1.6	3.3	4.8	1.6	5.4	1.6	5.3	ns
^t PZH	- OLIVEN	A or D	1	3.4	4.6	& 1	5.8	1	5.7	
t _{PZL}	CLKEN	A or B	1.2	3.9	6	1.2	7.3	1.2	7.2	ns
^t PHZ	CLKEN	A or B	1.7	3.9	5.2	1.7	6.2	1.7	5.8	no
t _{PLZ}] CLKEN	AUID	1.5	3.6	5.3	1.5	5.5	1.5	5.4	ns

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{Q} = 50 Ω , t_{f} \leq 2.5 ns, t_{f} \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



www.ti.com 11-Nov-2025

PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
						(4)	(5)		
SN74ABT16470DGGR	Active	Production	TSSOP (DGG) 56	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16470
SN74ABT16470DGGR.B	Active	Production	TSSOP (DGG) 56	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16470
SN74ABT16470DL	Active	Production	SSOP (DL) 56	20 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16470
SN74ABT16470DL.B	Active	Production	SSOP (DL) 56	20 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16470

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

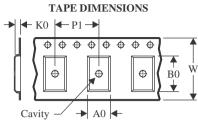
⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE MATERIALS INFORMATION

www.ti.com 25-Jul-2025

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

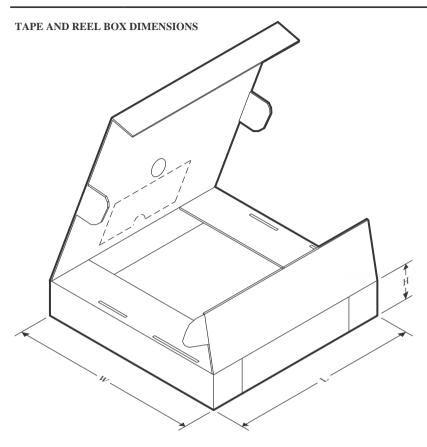


*All dimensions are nominal

Device	U	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	` '	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT16470DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.9	14.7	1.4	12.0	24.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 25-Jul-2025



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT16470DGGR	TSSOP	DGG	56	2000	356.0	356.0	45.0

PACKAGE MATERIALS INFORMATION

www.ti.com 25-Jul-2025

TUBE

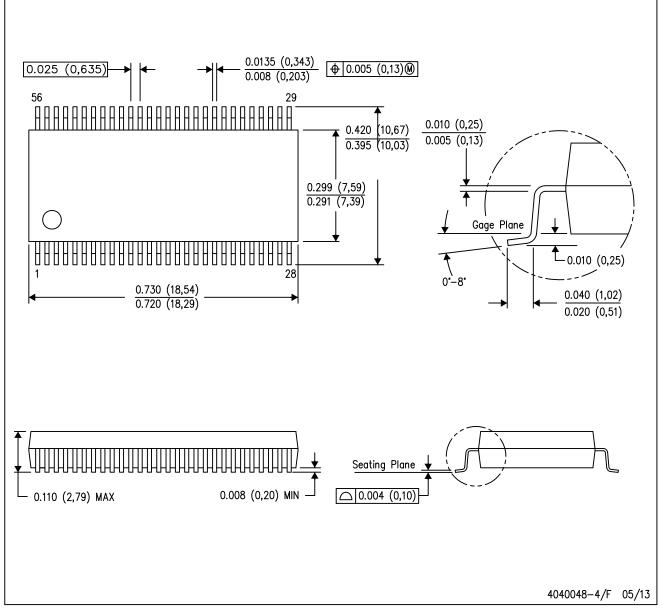


*All dimensions are nominal

	Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
ĺ	SN74ABT16470DL	DL	SSOP	56	20	473.7	14.24	5110	7.87
ĺ	SN74ABT16470DL.B	DL	SSOP	56	20	473.7	14.24	5110	7.87

DL (R-PDSO-G56)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

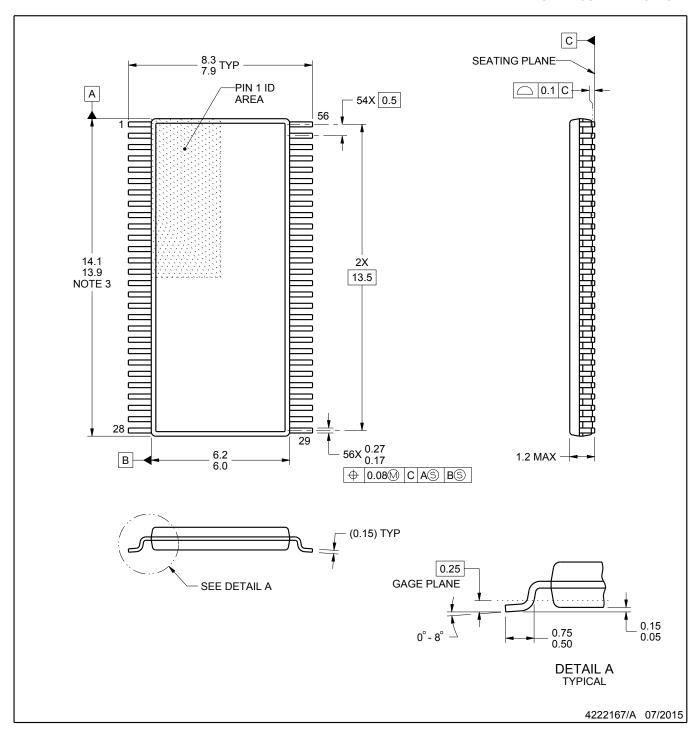
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.





SMALL OUTLINE PACKAGE



NOTES:

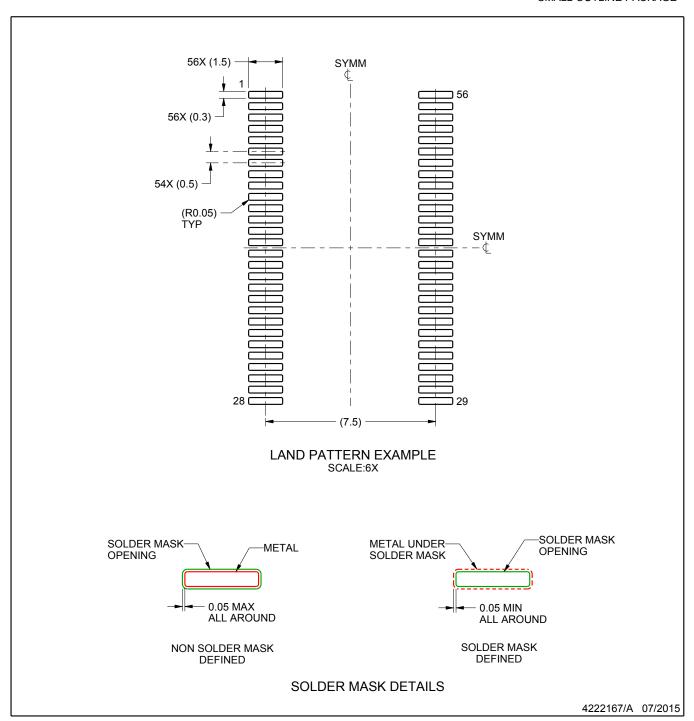
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
 4. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE

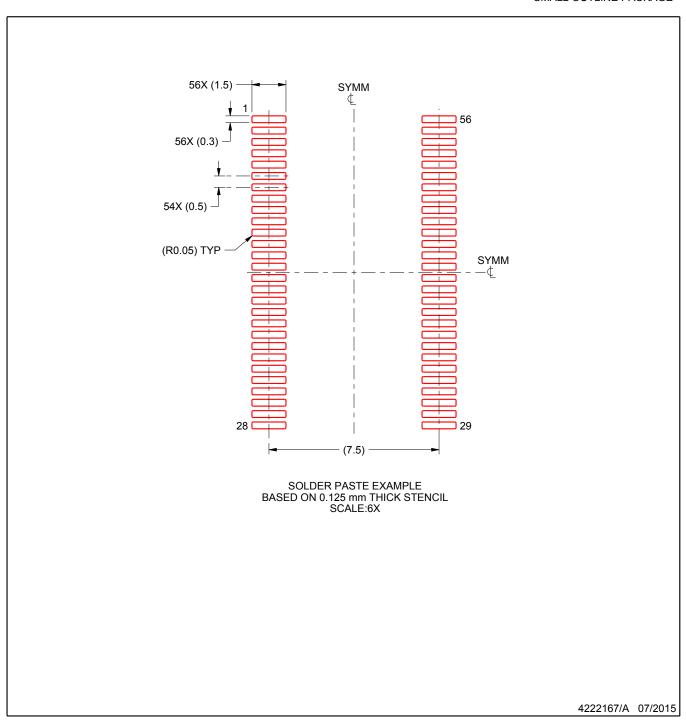


NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale, TI's General Quality Guidelines, or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2025, Texas Instruments Incorporated

Last updated 10/2025